

11-02-2001
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Attorney Docket No.: 053933-5012

To the Commissioner for Patents:
Please record the attached original documents or copy thereof.

ATTN: BOX ASSIGNMENT

1. Name of conveying party(ies):

Myung-Sam KANG
Keon-Yang PARK
Jang-Kyu KANG

10/29/01

Additional name(s) of conveying party(ies) attached?

Yes ☒ No

2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRO-MECHANICS CO., LTD.

Internal Address:

Street Address: 314, Maetan-3dong, Paldal-Gu,
Suwon, Kyunggi-Do 442-743,
Republic of Korea

City:

State:

Zip:

Additional name(s) & address(es) attached?

Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
Other _____

Execution Date: September 24, 2001

4. Application number(s) or patent number(s): NEW APPLICATION

If this document is being filed together with a new application the execution date of the application is:

September 24, 2001

A. Patent Application No. : B. Patent No.(s)

10/30/2001 EFLORES 00000026 09984282

02 FC:581

40.00 DP

Additional numbers attached: ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Robert J. Gaybrick

Internal Address: Morgan, Lewis & Bockius LLP

Street Address: 1800 M Street, N.W.

City: Washington State: D.C. Zip: 20036

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R §3.41): \$40.00

☒ Enclosed

☐ Authorized to be charged to deposit account 50-0310

8. Deposit account number: 50-0310

Attach duplicate of page if paying by deposit account

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert J. Goodell

Name of Person Signing

Reg. No. 41,040

Robert J. Goodell

Signature

October 29, 2001

Date

Total number of pages including cover sheet, attachments and documents: 3

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled: **METHOD FOR PREPARING HIGH PERFORMANCE BALL GRID ARRAY BOARD AND JIG APPLICABLE TO SAID METHOD**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Application No. _____); and

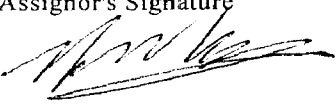
WHEREAS, **Samsung Electro-Mechanics Co., Ltd.**, a corporation of Korea, whose post office address is **314, Maetan-3dong, Paldal-gu, Suwon, Kyunggi-do 442-743, Republic of Korea** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

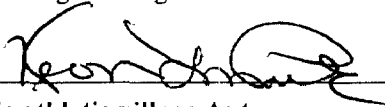
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

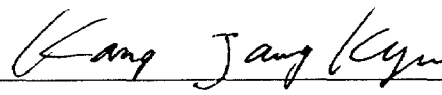
AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known. **October 29, 2001**

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s):

Full Name of Sole or First Assignor Myung -Sam KANG	Assignor's Signature 	Date 2001. 9. 24
Address 86-12, Goejeong-dong, Seo-gu, Daejeon 302-200, Korea		Citizenship KOREA
Names of additional inventors attached ☒ Yes ☐ No		

Full Name of Sole or First Assignor Keon-Yang PARK	Assignor's Signature 	Date <i>Sept. 24, 2001</i>
Address 305-605, Olympic athletic village Apt., Oryun-dong 89, Songpa-gu, Seoul 138-788, Korea	Citizenship USA KOREA 	
Names of additional inventors attached ☒ Yes ☐ No		

Full Name of Sole or First Assignor Jang-Kyu KANG	Assignor's Signature 	Date <i>9. 24. 2001</i>
Address 306-1301, Expo Apt., Jeonmin-dong, Yuseong-gu, Daejeon, 305-761, Korea	Citizenship KOREA	
Names of additional inventors attached ☐ Yes ☒ No		